

**Figure 1: Printing and Plating. Typical schematic procedure for making stamp from photoresist master pattern, inking with thiol, stamping thiol on gold to form SAM protective pattern, etching away unprotected gold, electroless plating of copper lines on top of remaining gold.**

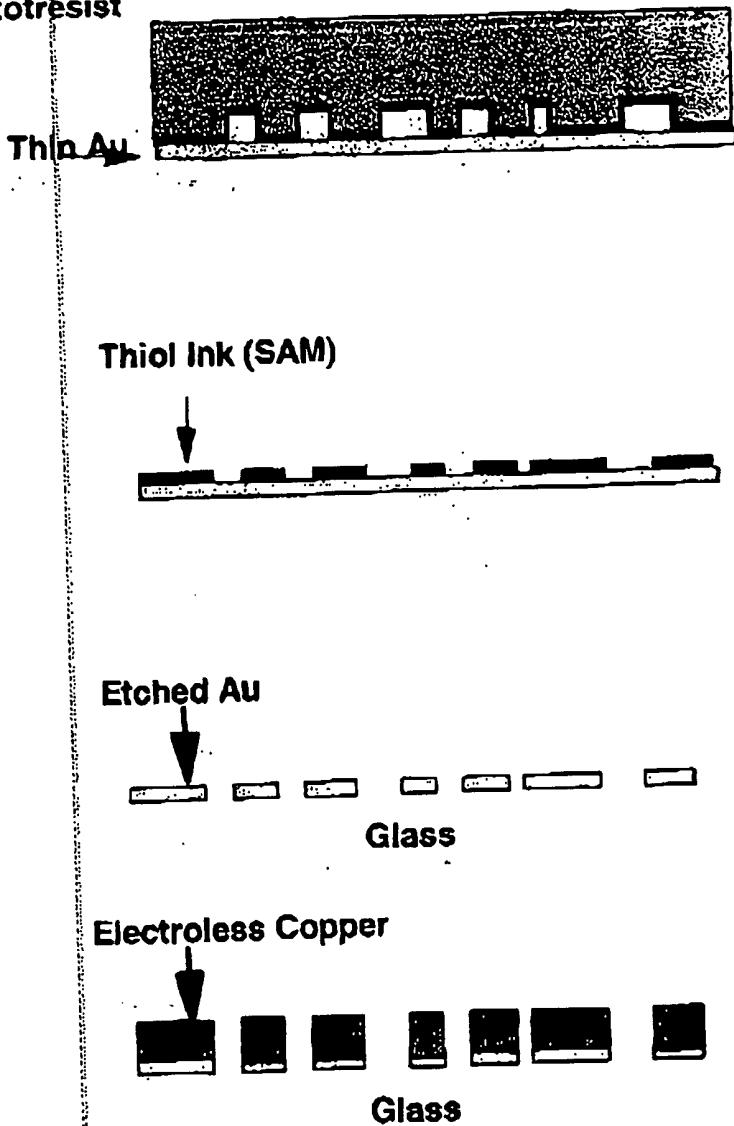
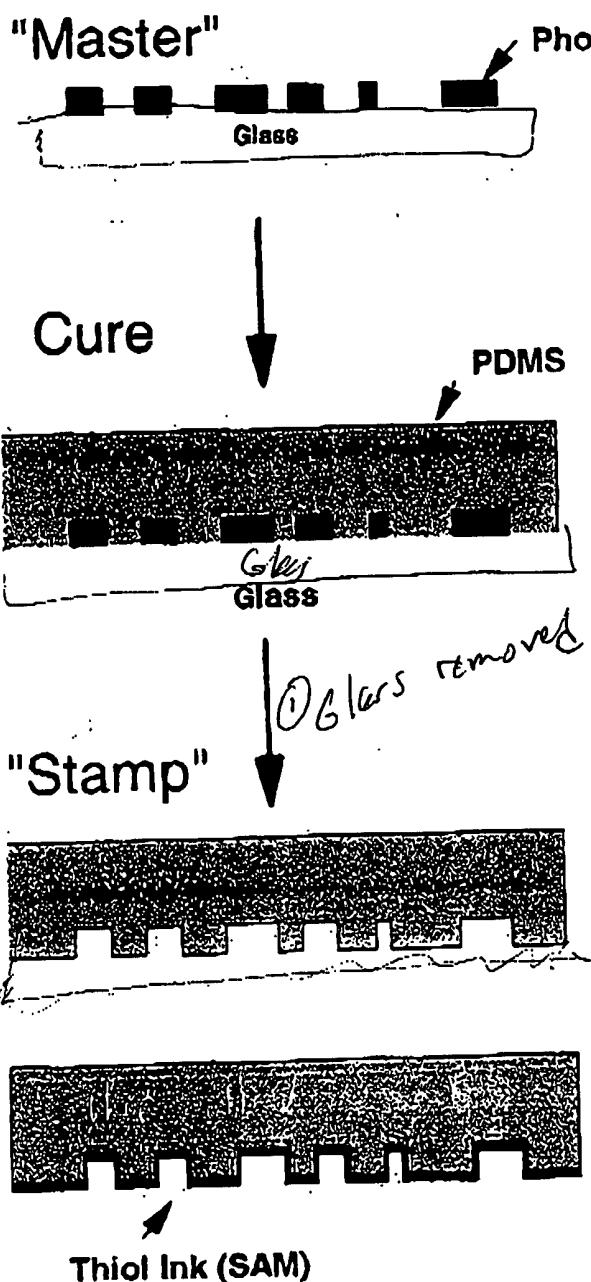
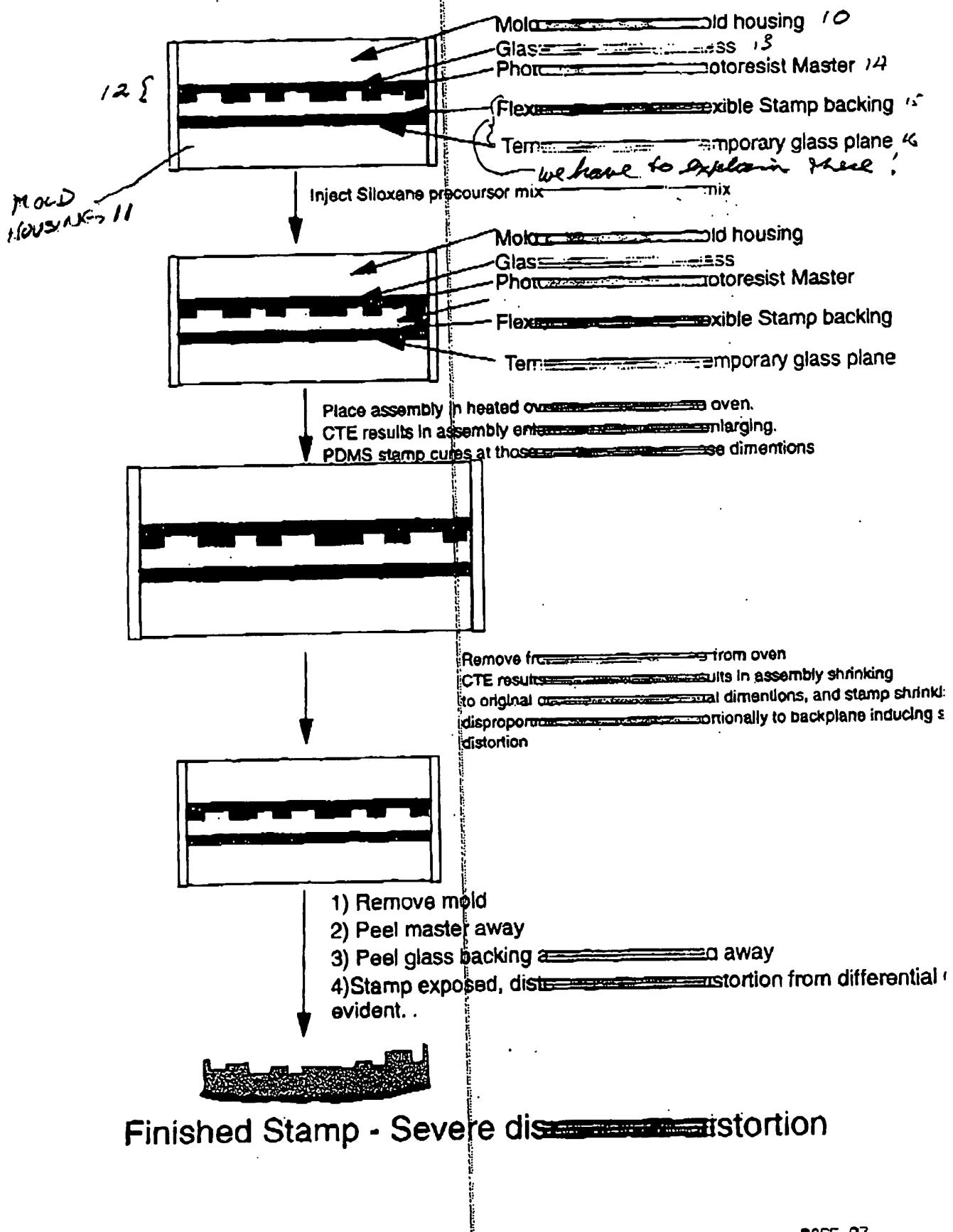
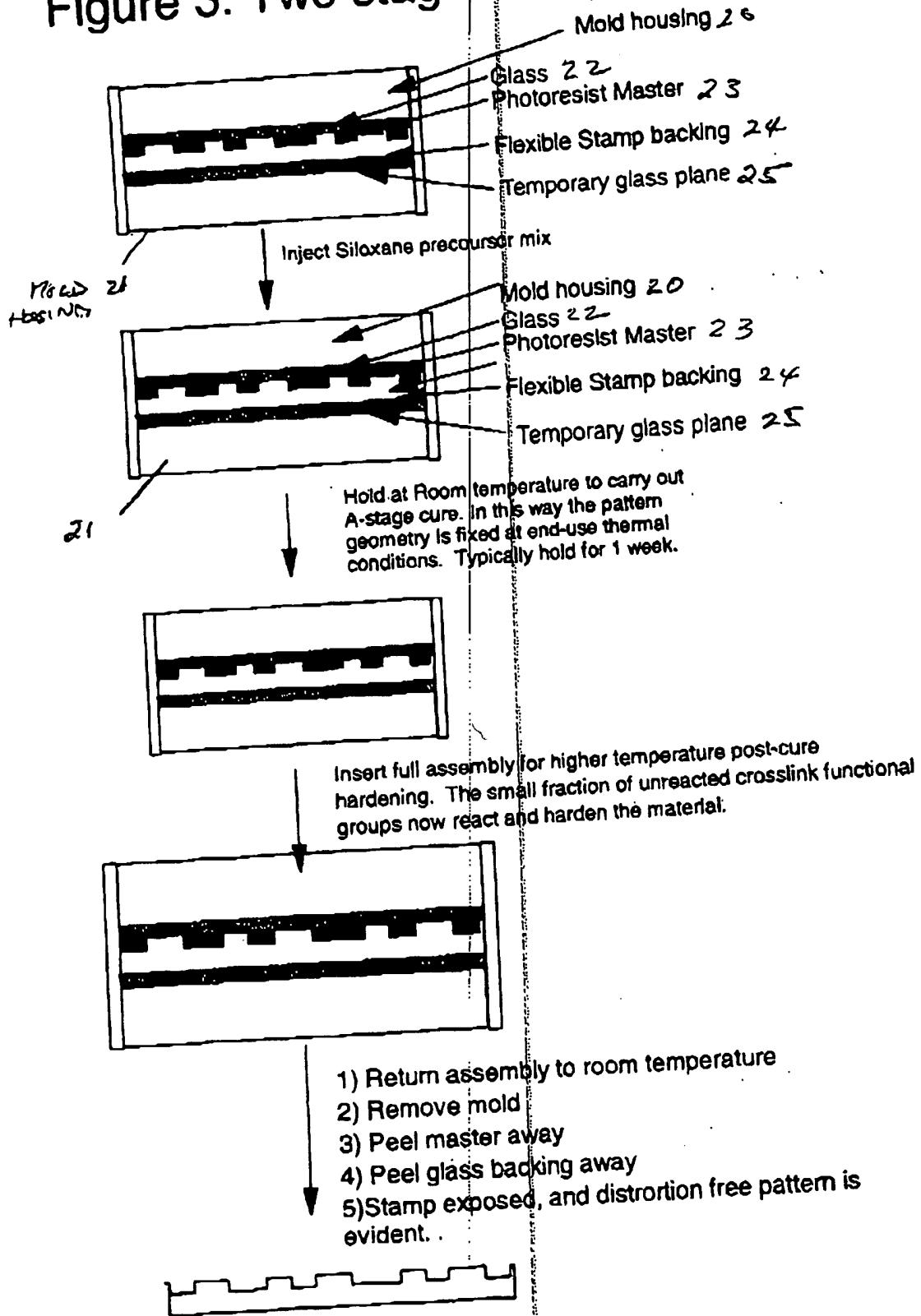


Figure 2: Standard one-step curing me



# Figure 3: Two stage curing of Siloxane stamp.



Finished Stamp | Little distortion evident

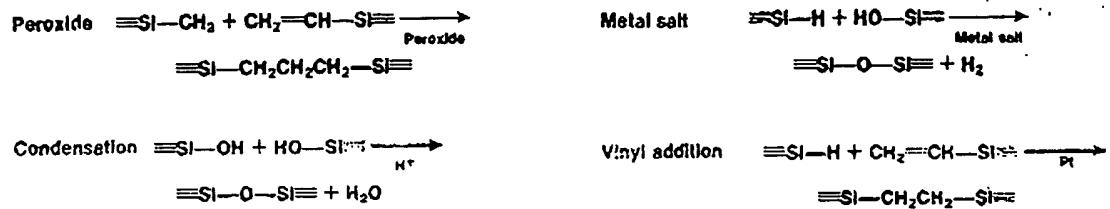


Figure 4 Silicone curing systems

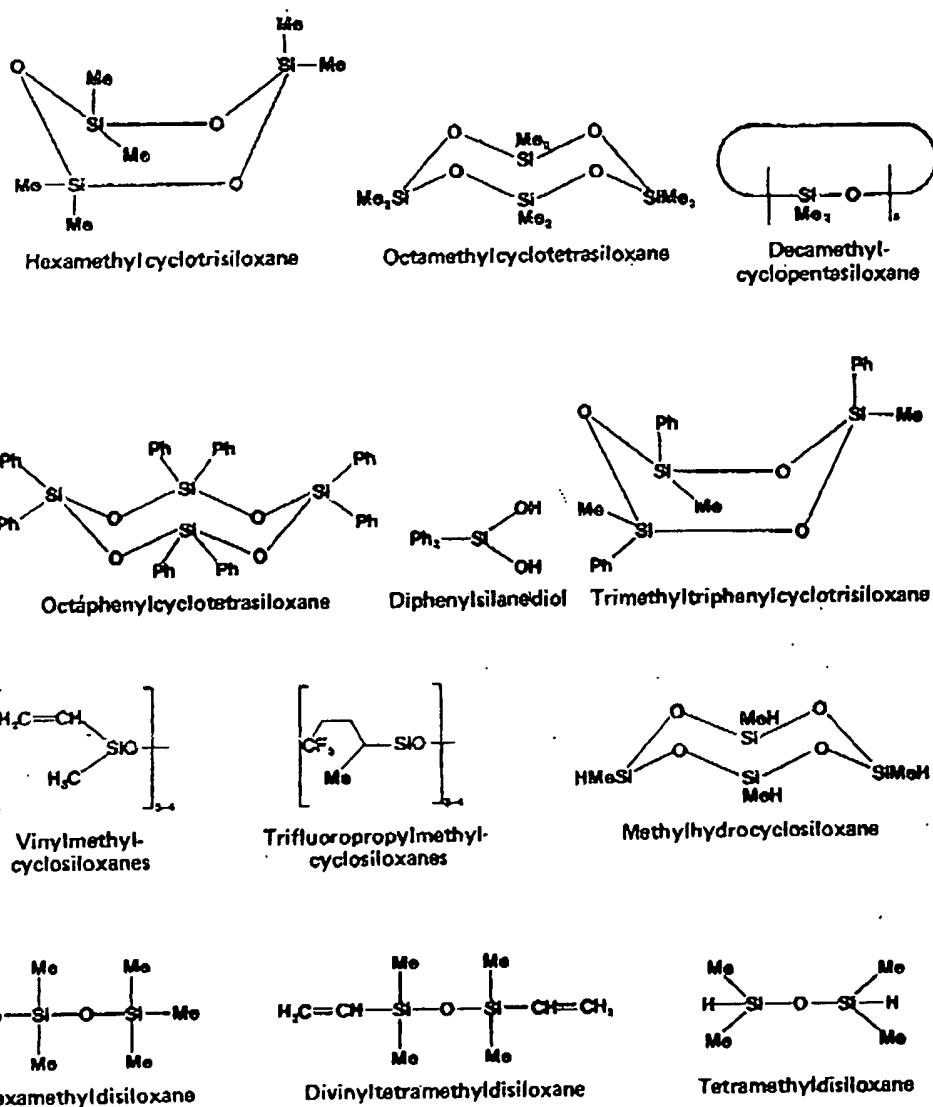


Figure 5 Silicone monomers and terminators